



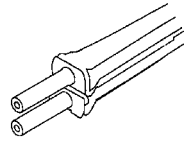
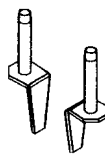
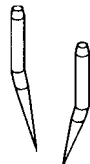
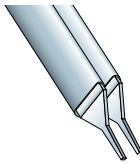
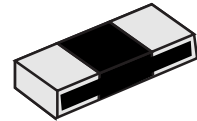
7711  
Rework

Revision: **B**  
Date: 11/07

Number: **3.3.2**

## Chip Component Removal

### Tweezer Method



Board Type: R, F, W, C  
See 1.4.2  
Skill Level: Intermediate  
See 1.4.3  
Level of Conformance: High  
See 1.5.1

### GENERAL REQUIREMENTS

Clauses 1.7 (Basic Considerations), 1.8 (Workstations, Tools, Materials and Processes) and 1.9 (Lead Free) provide important information and guidance about the use of this procedure, including but not limited to tin-lead and lead-free alloys. This procedure is also applicable to lead free products.

### EQUIPMENT REQUIRED

Soldering system  
Chip removal tips  
Tweezer handpiece

### MATERIALS

Flux  
Cleaner

### PROCEDURE

1. Remove conformal coating (if any) and clean work area of any contamination, oxides or residues.
2. Install chip removal tips into tweezer handpiece.
3. Start with tip temperature of approximately 315°C and change as necessary.
4. Apply flux to the component terminations. (See Figure 1.)
5. Clean the tip, Procedure 2.8.
6. Lower tips over component and squeeze handpiece to contact both solder joints. (See Figure 2.)
7. Confirm complete solder melt of both joints and lift component from PCB. (See Figures 3 & 4.)

**NOTE:** Chip components may have adhesive between the body and the board. If adhesive is used, it may be necessary to slightly turn the component to allow the component to be removed from the board. This must only be accomplished after complete solder melt to prevent damage.

8. Release component onto a heat resistant surface.
9. Prepare lands for component replacement.
10. Clean as applicable and inspect to established workmanship requirements.

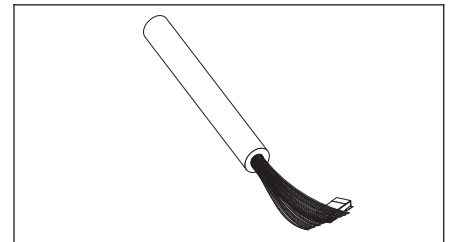


Figure 1 Flux Component

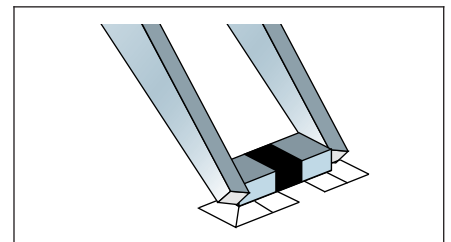


Figure 2 Position Tip

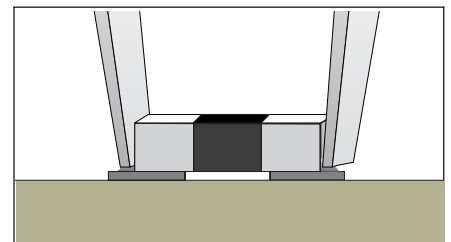


Figure 3 Melt Joints

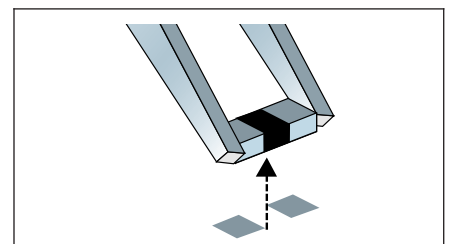


Figure 4 Lift Component